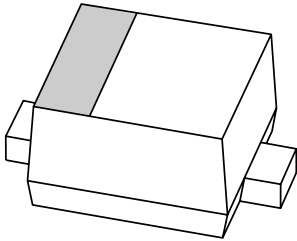


DATA SHEET

www.DataSheet4U.com



BAP1321-01 Silicon PIN diode

Preliminary specification

2001 Nov 01

Silicon PIN diode

BAP1321-01

FEATURES

- High voltage, current controlled
- RF resistor for RF attenuators and switches
- Low diode capacitance
- Low diode forward resistance
- Very low series inductance
- For applications up to 3 GHz.

APPLICATIONS

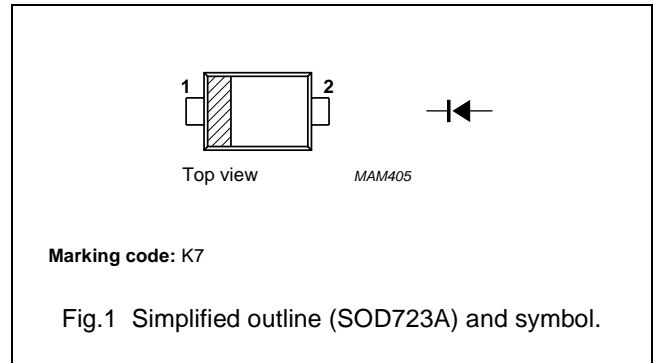
- RF attenuators and switches.

DESCRIPTION

Planar PIN diode in a SOD723A ultra small plastic SMD package.

PINNING

PIN	DESCRIPTION
1	cathode
2	anode



LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_R	continuous reverse voltage		–	60	V
I_F	continuous forward current		–	100	mA
P_{tot}	total power dissipation	$T_s = 90\text{ °C}$	–	315	mW
T_{stg}	storage temperature		–65	+150	°C
T_j	junction temperature		–65	+150	°C

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ELECTRICAL CHARACTERISTICS

$T_j = 25\text{ }^\circ\text{C}$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V_F	forward voltage	$I_F = 50\text{ mA}$	0.95	1.1	V
I_R	reverse leakage current	$V_R = 60\text{ V}$	–	0.1	μA
		$V_R = 20\text{ V}$	–	tbd	μA
C_d	diode capacitance	$V_R = 0; f = 1\text{ MHz}$	0.32	–	pF
		$V_R = 1\text{ V}; f = 1\text{ MHz}$	0.28	–	pF
		$V_R = 20\text{ V}; f = 1\text{ MHz}$	0.22	0.32	pF
r_D	diode forward resistance	$f = 100\text{ MHz}$; note 1			
		$I_F = 0.5\text{ mA}$	3.2	5.0	Ω
		$I_F = 1\text{ mA}$	2.3	3.6	Ω
		$I_F = 10\text{ mA}$	1.1	1.8	Ω
$ S_{21} ^2$	isolation	$V_R = 0; f = 900\text{ MHz}$	15.7	–	dB
		$V_R = 0; f = 1800\text{ MHz}$	10.8	–	dB
		$V_R = 0; f = 2450\text{ MHz}$	8.7	–	dB
		$I_F = 0.5\text{ mA}; f = 900\text{ MHz}$	0.26	–	dB
$ S_{21} ^2$	insertion loss	$I_F = 0.5\text{ mA}; f = 1800\text{ MHz}$	0.28	–	dB
		$I_F = 0.5\text{ mA}; f = 2450\text{ MHz}$	0.31	–	dB
		$I_F = 1\text{ mA}; f = 900\text{ MHz}$	0.20	–	dB
$ S_{21} ^2$	insertion loss	$I_F = 1\text{ mA}; f = 1800\text{ MHz}$	0.23	–	dB
		$I_F = 1\text{ mA}; f = 2450\text{ MHz}$	0.25	–	dB
		$I_F = 10\text{ mA}; f = 900\text{ MHz}$	0.15	–	dB
$ S_{21} ^2$	insertion loss	$I_F = 10\text{ mA}; f = 1800\text{ MHz}$	0.18	–	dB
		$I_F = 10\text{ mA}; f = 2450\text{ MHz}$	0.21	–	dB
		$I_F = 100\text{ mA}; f = 900\text{ MHz}$	0.10	–	dB
$ S_{21} ^2$	insertion loss	$I_F = 100\text{ mA}; f = 1800\text{ MHz}$	0.13	–	dB
		$I_F = 100\text{ mA}; f = 2450\text{ MHz}$	0.16	–	dB
		τ_L	charge carrier life time	when switched from $I_F = 10\text{ mA}$ to $I_R = 6\text{ mA}$; $R_L = 100\ \Omega$; measured at $I_R = 3\text{ mA}$	0.5
L_S	series inductance	$I_F = 100\text{ mA}; f = 100\text{ MHz}$	0.6	–	nH

Note

1. Guaranteed on AQL basis: inspection level S4, AQL 1.0.

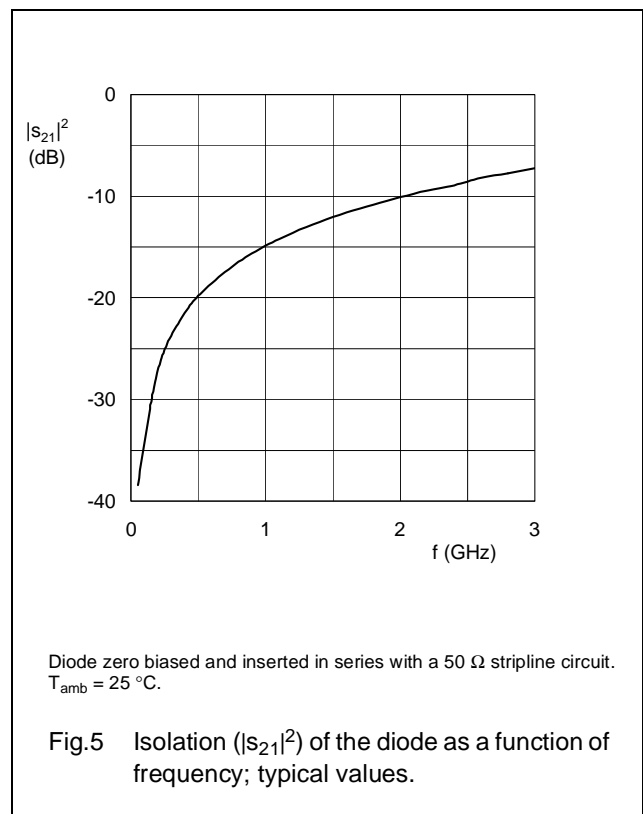
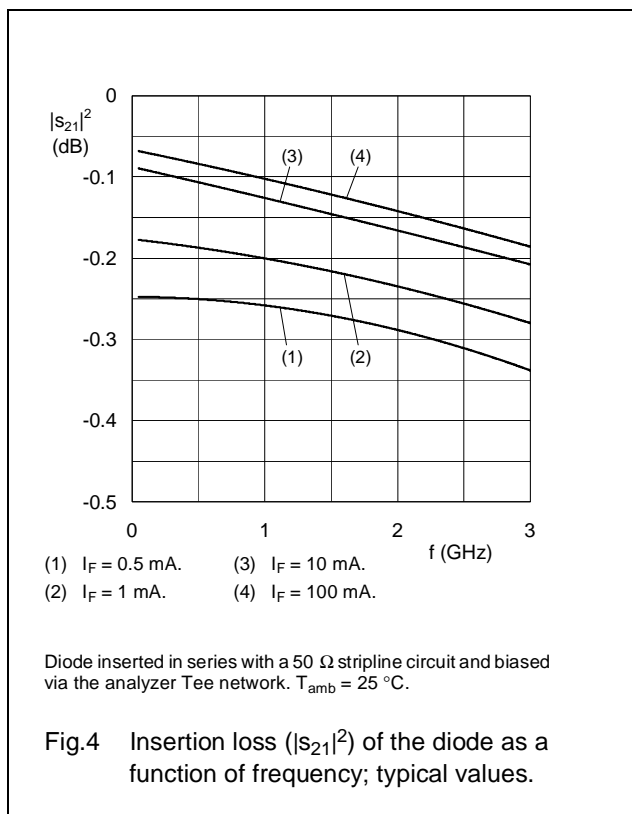
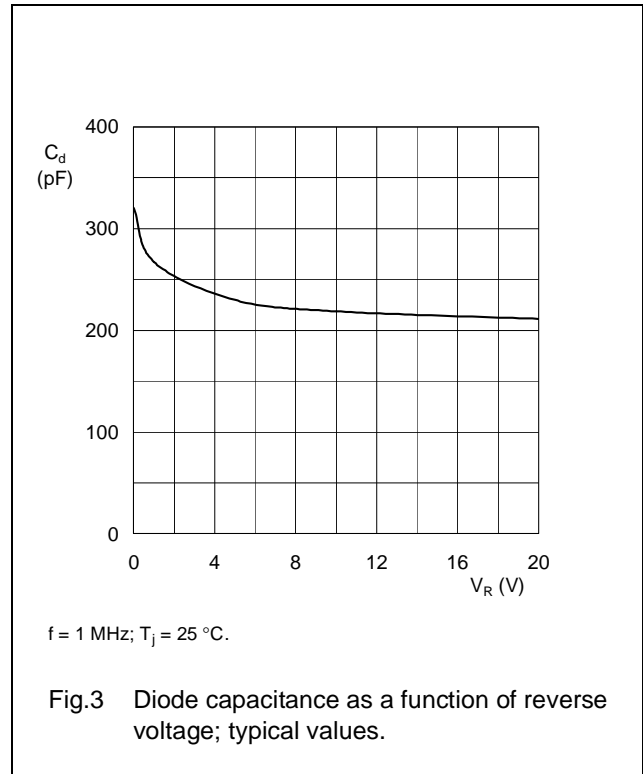
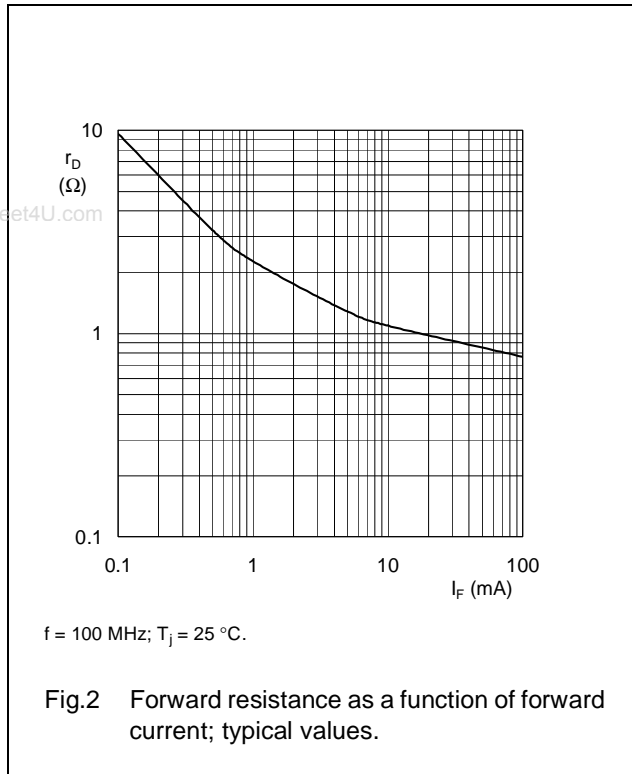
THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	VALUE	UNIT
$R_{th\ j-s}$	thermal resistance from junction to soldering point	190	K/W

Silicon PIN diode

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GRAPHICAL DATA



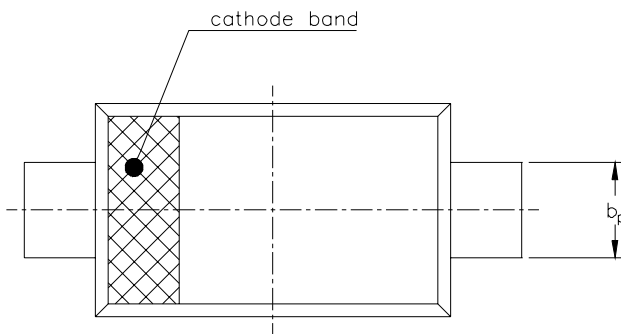
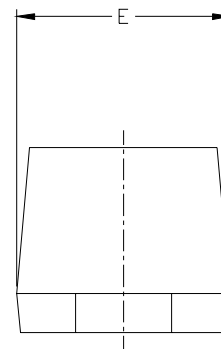
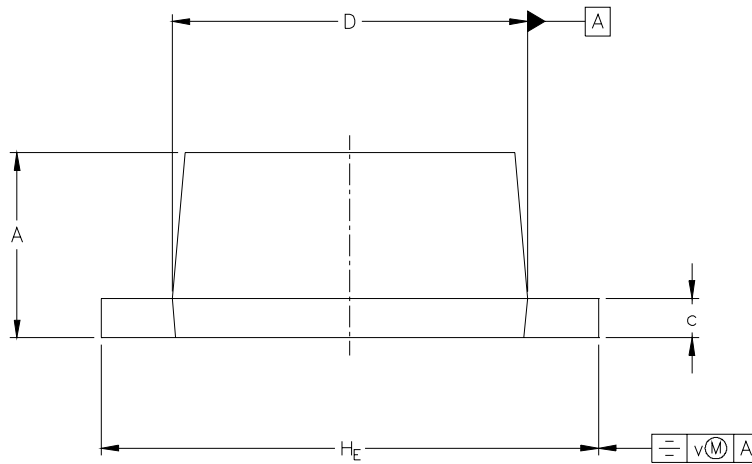
Silicon PIN diode

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PACKAGE OUTLINE

SOD723A

Plastic surface mounted package; 2 leads



UNIT	A	b _p	c	D	E	H _E	v
mm	0.49 0.55	0.25 0.32	0.08 0.15	0.95 1.05	0.55 0.65	1.35 1.45	0.1

PACKAGE OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ		
SOD723A PUBLICATION DRAWING					01-09-06

UNDER DEVELOPMENT

Silicon PIN diode

BAP1321-01

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Contact information

For additional information please visit <http://www.semiconductors.philips.com>. Fax: **+31 40 27 24825**

For sales offices addresses send e-mail to: sales.addresses@www.semiconductors.philips.com.

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